What is claimed is:

1. A substrate cleaning apparatus comprising:

a substrate support mechanism configured to support a substrate;

a roll-type first cleaning member configured to clean a first surface of the substrate by rotating while being in contact with a bevel and/or an edge of the first surface of the substrate;

a roll-type second cleaning member facing the first cleaning member and configured to clean a second surface of the substrate by rotating while being in contact with a bevel and/or an edge of the second surface of the substrate;

a first nozzle configured to supply cleaning liquid to the first surface of the substrate in a direction toward an edge of the substrate; and

a second nozzle configured to supply cleaning liquid to the second surface of the substrate in a direction toward an edge of the substrate, wherein

a rotation axis of the first cleaning member and the second cleaning member are in parallel with the substrate, and

each of the first cleaning member and the second cleaning member comprises a plurality of large diameter portions and a plurality of small diameter portions,

the small diameter portion of the second cleaning member is located facing the large diameter portion of the

first cleaning member, the large diameter portion of the second cleaning member is located facing the small diameter portion of the first cleaning member, and the first cleaning member and the second cleaning member rotate without being in contact with each other,

the large diameter portions and the small diameter portions are alternately arranged along longitudinal directions of the first cleaning member and the second cleaning member, thereby a plurality of grooves are formed in a circumferential direction, each of the grooves are separated from the adjacent grooves by the large diameter portions and becomes independent shape,

the cleaning liquid from the first nozzle flows through the grooves of the first cleaning member and is discharged to the outer circumferential direction of the substrate, and

the cleaning liquid from the second nozzle flows through the grooves of the second cleaning member and is discharged to the outer circumferential direction of the substrate,

the first cleaning member can be moved in a radial direction of the substrate, and located at a first retreated position away from a position where the substrate is arranged in a direction perpendicular to an outer circumferential direction during standby in which cleaning of the substrate is not performed, and

the second cleaning member can be moved in the

radial direction of the substrate, and located at a second retreated position away from a position where the substrate is arranged in a direction perpendicular to an outer circumferential direction during standby in which cleaning of the substrate is not performed.

2. The substrate cleaning apparatus according to claim 1, wherein

the substrate support mechanism is configured to hold the substrate and rotate the substrate.

3. The substrate cleaning apparatus according to claim 1 or 2, wherein

a rotation direction of the first cleaning member is a direction from a center of the substrate toward an edge of the substrate at a position where the first cleaning member is in contact with the substrate.

4. The substrate cleaning apparatus according to one of claims 1-3, further comprising:

an actuator that swings the first cleaning member in a tangential direction, a radial direction, and/or a vertical direction of the substrate when the substrate is cleaned.

5. The substrate cleaning apparatus according to one of claims 1-4, wherein

the substrate has a polygonal shape, and

the substrate support mechanism moves the substrate in a direction along a side of the substrate and the first cleaning member comes into contact with a bevel and/or an

edge along a side of the substrate.

6. The substrate cleaning apparatus according to one of claims 1-5, wherein

the substrate has a polygonal shape, and

the substrate cleaning apparatus further comprises a moving mechanism configured to move the first cleaning member in a direction along a side of the substrate.